

Features

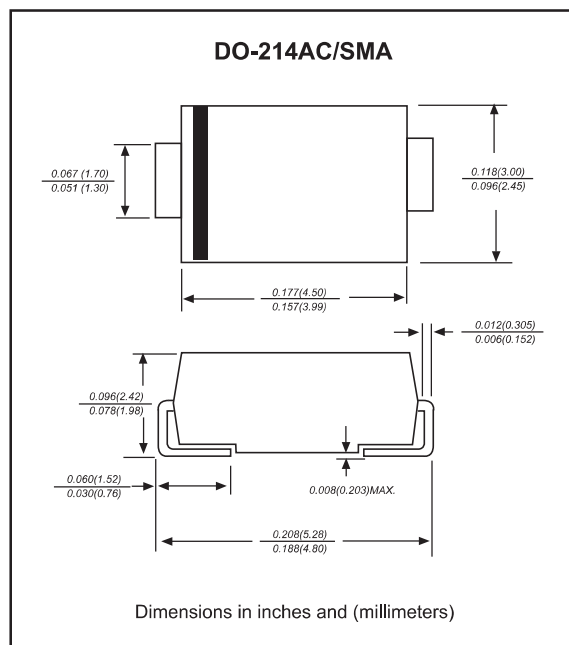


- 400W peak pulse power capability with a 10/1000 μ s waveform, repetition rate (duty cycle): 0.01%.
- Low profile surface mounted application in order to optimize board space.
- Excellent clamping capability.
- Low incremental surge resistance.
- Fast response time from 0V to VBR, typically less than 1 ps for uni-directional & 5 ns for bi-directional types.
- Glass passivated chip junction.
- Lead-free parts meet RoHS requirements.
- Compliant to Halogen-free

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AC / SMA
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbols	Value	Unit
Peak power dissipation with a 10/1000 μ s waveform ⁽¹⁾	P_{PP}	400	W
Peak pulse current with a 10/1000 μ s waveform ⁽¹⁾	I_{PP}	50	A
Power dissipation on infinite heatsink at $T_L = 75^{\circ}\text{C}$	P_D	1.0	W
Peak forward surge current, 8.3 ms single half sinewave unidirectional only ⁽²⁾	I_{FSM}	40	A
Maximum instantaneous forward voltage at 10 A for unidirectional only	V_F	3.5	V
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^{\circ}\text{C}$

Note:

1) Non-repetitive current pulse per Fig.5 and derated above $T_A = 25^{\circ}\text{C}$ per Fig.1 ;

2) Measured on 8.3 ms single half sine-wave or equivalent square wave, duty cycle = 4 pulses per minute maximum ;

Part Number		Device Marking Code		Reverse Stand-off Voltage	Breakdown Voltage V_{BR} @ I_T		Test Current	Max. Clamping Voltage @ I_{PP}	Max. Peak Pulse Current	Max. Reverse Leakage @ V_{RWM}
UNI-POLAR	BI-POLAR	UNI	BI	$V_{RWM}(V)$	Min.(V)	Max.(V)	$I_T(mA)$	$V_{C MAX}(V)$	$I_{PP}(A)$	$I_R(\mu A)$
SMAJ3.3A	SMAJ3.3CA	3V3	3V3C	3.3	5.00	6.50	10	8.0	50	600

Rating and characteristic curves

Fig.1 - Peak Pulse Power Rating Curve

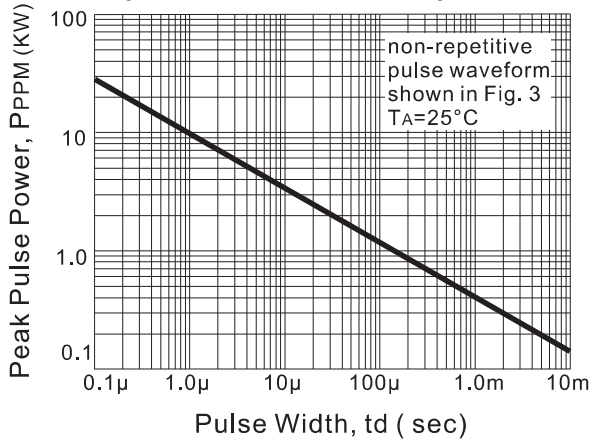


Fig.2 - Pulse Derating Curve

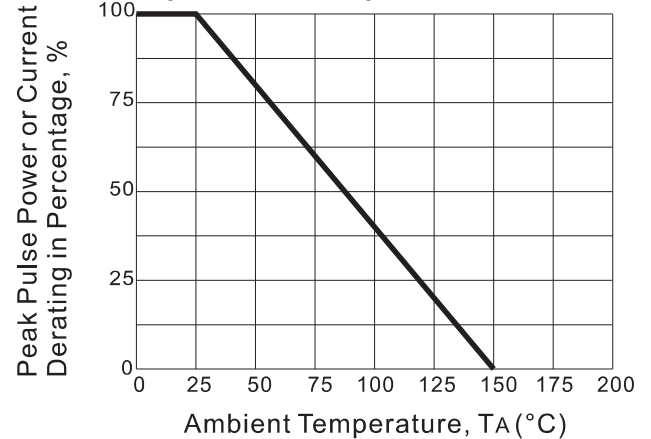


Fig.3 - Pulse Waveform

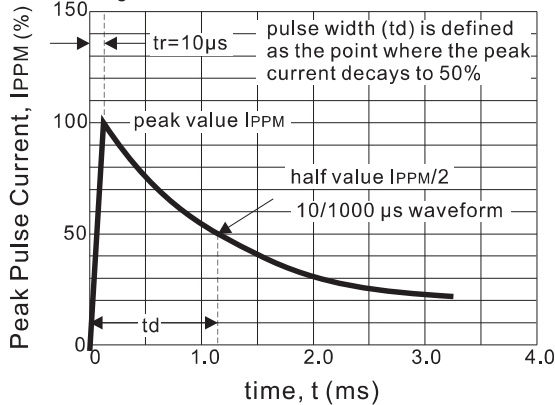


Fig.4 - Typical Junction Capacitance

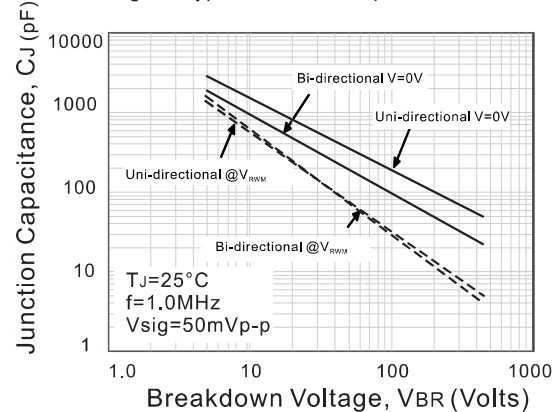


Fig.5 - Steady State Power Derating Curve

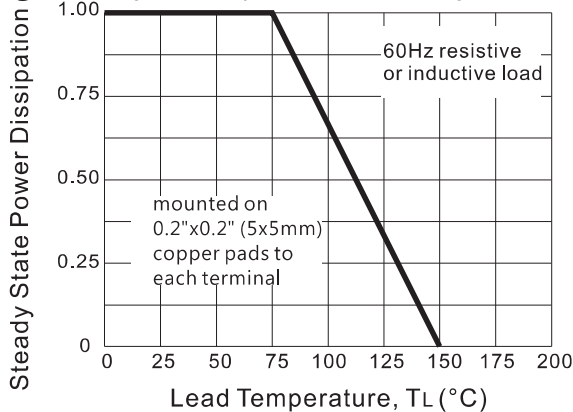
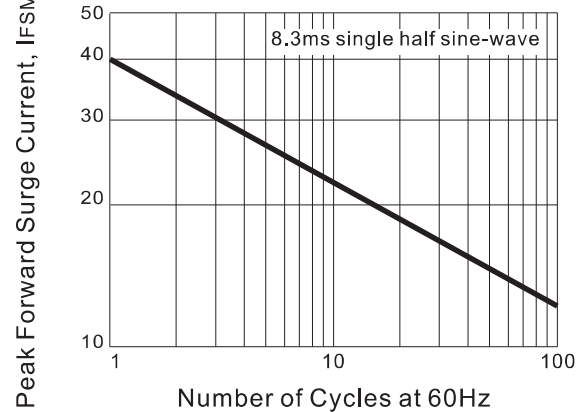


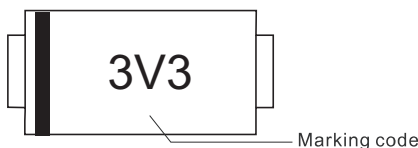
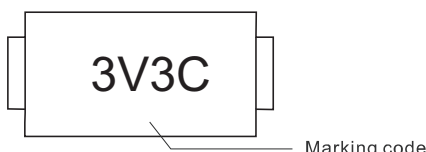
Fig.6 - Maximum Non-Repetitive Forward Surge Current



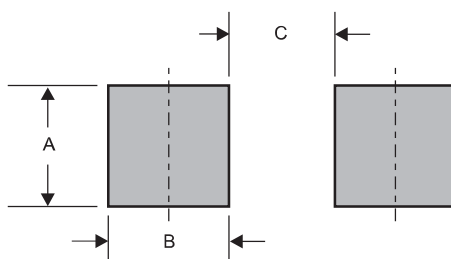
Pinning information

Pin	Simplified outline	Symbol
Uni-Directional Pin1 cathode Pin2 anode		
Bi-Directional		

Marking

Type number	Example
Uni-Directional	
Bi-Directional	

Suggested solder pad layout

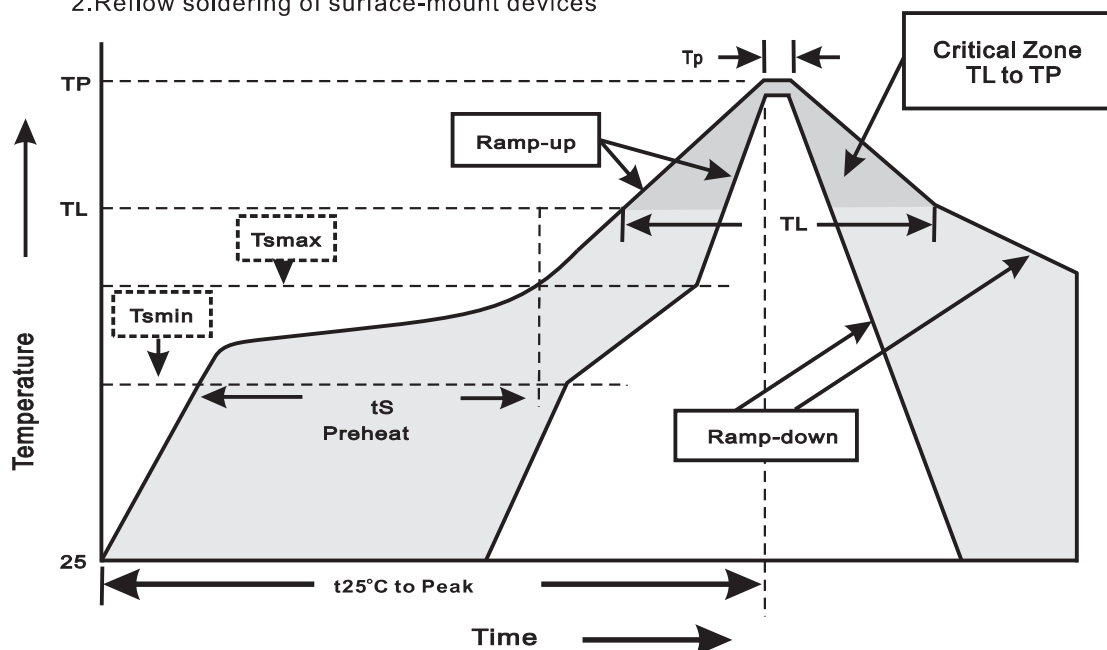


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.063 (1.60)	0.059 (1.50)	0.110 (2.80)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{min}) -Temperature Max(T_{max}) -Time(min to max)(t_s)	150°C 200°C $60\sim 120\text{sec}$
T_{max} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C $60\sim 260\text{sec}$
Peak Temperature(T_P)	$255^{\circ}\text{C}-0/+5^{\circ}\text{C}$
Time within 5°C of actual Peak Temperature(t_P)	$10\sim 30\text{sec}$
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$